

Bill of Materials

TI DESIGNS

TIPD170: Single-Supply Strain Gauge in a Bridge Configuration Reference Design

Item #	Quantity	Designator	Value	PartNumber	Manufacturer	Description	DigiKey Part Number
1	3	C1, C11, C12	10uF	TPSB106M020R1000	AVX	CAP, TANT, 10uF, 20V, +/-20%, 1 ohm, 3528-21 SMD	478-4087-1-ND
2	3	C3, C7, C13	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	490-5307-1-ND
3	2	C5, C8	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	478-3726-1-ND
4	1	J1		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	ED1514-ND
5	3	R1, R2, R3	120	RG1608N-121-W-T1	Susumu	RES, 120, 0.05%, 1/10 W, 0603	RG16P120BCT-ND
6	4	R4, R6, R7, R8	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	541-0.0GCT-ND
7	1	R5	1.27k	ERA-3AEB1271V	Panasonic Electronic Components	RES, 1.27K OHM, 1/10W, 0.1%, 0603, SMD	541-1.27KHCT-ND
8	1	Rg	100	RNCF1206TKY100R	Stackpole Electronics Inc.	RES 100 OHM 1/4W 0.01% 1206	311-100HRCT-ND
9	1	TP1	Red	5005	Keystone	Test Point, TH, Compact, Red	5005K-ND
10	4	TP2, TP4, TP5, TP6	Black	5006	Keystone	Test Point, TH, Compact, Black	5006K-ND
11	1	TP7	Orange	5008	Keystone	Test Point, Compact, Orange, TH	5008K-ND
12	1	TP8	White	5007	Keystone	Test Point, Compact, White, TH	5007K-ND
13	1	U1		INA333AIDGK	Texas Instruments	Micro-Power, Zero-Drift, Rail-to-Rail Out Instrumentation Amplifier	296-23564-1-ND
14	1	U2		REF5025AIDGKR	Texas Instruments	Low Noise, Very Low Drift, Precision Voltage Reference,	REF5025AIDGKR-ND
15	4	U90, U91, U92, U93		2205	Keystone	STANDOFF HEX 4-40THR ALUM 1"L	2205K-ND
16	4	U94, U95, U96, U97		PMSSS 440 0025 PH	B&F Fastener Supply	MACHINE SCREW PAN PHILLIPS 4-40	H703-ND
17	1	RI	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0k ohm, 1%, 0.1W, 0603	
18	0	C9	1000pF	CX0603MRX7R0BB102	Yageo America	CAP, CERM, 1000 pF, 100 V, +/- 20%, X7R, 0603	
19	0	C10	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	

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